

Gerard Cummins

List of Publications by Citations

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Version: 2024-04-28

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

29
papers

792
citations

13
h-index

28
g-index

43
ext. papers

998
ext. citations

4.7
avg, IF

4.38
L-index

#	Paper	IF	Citations
29	Inkjet printing of conductive materials: a review. <i>Circuit World</i> , 2012 , 38, 193-213	0.7	294
28	Two-phase flow instabilities in a silicon microchannels heat sink. <i>International Journal of Heat and Fluid Flow</i> , 2009 , 30, 854-867	2.4	100
27	Wireless Power Transfer Techniques for Implantable Medical Devices: A Review. <i>Sensors</i> , 2020 , 20,	3.8	47
26	Experimental investigation of non-uniform heating effect on flow boiling instabilities in a microchannel-based heat sink. <i>International Journal of Thermal Sciences</i> , 2011 , 50, 309-324	4.1	45
25	Intelligent magnetic manipulation for gastrointestinal ultrasound. <i>Science Robotics</i> , 2019 , 4,	18.6	40
24	In Vivo Characterization of a Wireless Telemetry Module for a Capsule Endoscopy System Utilizing a Conformal Antenna. <i>IEEE Transactions on Biomedical Circuits and Systems</i> , 2018 , 12, 95-105	5.1	38
23	Experimental pool boiling investigations of FC-72 on silicon with artificial cavities and integrated temperature microsensors. <i>Experimental Thermal and Fluid Science</i> , 2010 , 34, 422-433	3	32
22	Gastrointestinal diagnosis using non-white light imaging capsule endoscopy. <i>Nature Reviews Gastroenterology and Hepatology</i> , 2019 , 16, 429-447	24.2	23
21	Miniaturized 3-D Cross-Type Receiver for Wirelessly Powered Capsule Endoscopy. <i>IEEE Transactions on Microwave Theory and Techniques</i> , 2019 , 67, 1985-1993	4.1	18
20	Carbon screen-printed electrodes on ceramic substrates for label-free molecular detection of antibiotic resistance. <i>Journal of Interdisciplinary Nanomedicine</i> , 2016 , 1, 93-109	4	16
19	Investigation of Flow Distribution in Microchannels Heat Sinks. <i>Heat Transfer Engineering</i> , 2009 , 30, 1049-1057	1.057	15
18	Ultrasound capsule endoscopy: sounding out the future. <i>Annals of Translational Medicine</i> , 2017 , 5, 201	3.2	15
17	Nanocomposite-Based Microstructured Piezoresistive Pressure Sensors for Low-Pressure Measurement Range. <i>Micromachines</i> , 2018 , 9,	3.3	15
16	In-Vivo Evaluation of Microultrasound and Thermometric Capsule Endoscopes. <i>IEEE Transactions on Biomedical Engineering</i> , 2019 , 66, 632-639	5	13
15	Luminally expressed gastrointestinal biomarkers. <i>Expert Review of Gastroenterology and Hepatology</i> , 2017 , 11, 1119-1134	4.2	10
14	Optimization and characterization of Drop-on-Demand inkjet printing process for platinum organometallic inks 2011 ,		10
13	Sensors for Fetal Hypoxia and Metabolic Acidosis: A Review. <i>Sensors</i> , 2018 , 18,	3.8	9

12	Optimised co-electrodeposition of FeCo alloys for maximum magnetostriction effect. <i>Sensors and Actuators A: Physical</i> , 2015 , 223, 91-96	3.9	9
11	Progress towards a multi-modal capsule endoscopy device featuring microultrasound imaging 2016 ,		8
10	Ultrasound Capsule Endoscopy With a Mechanically Scanning Micro-ultrasound: A Porcine Study. <i>Ultrasound in Medicine and Biology</i> , 2020 , 46, 796-804	3.5	6
9	Ultrasound mediated delivery of quantum dots from a proof of concept capsule endoscope to the gastrointestinal wall. <i>Scientific Reports</i> , 2021 , 11, 2584	4.9	6
8	Design of conformal wideband antennas for capsule endoscopy within a body tissue environment 2016 ,		5
7	Experimental Investigation of Non-Uniform Heating on Flow Boiling Instabilities in a Microchannels Based Heat Sink 2009 ,		4
6	Challenges in developing collaborative interdisciplinary research between gastroenterologists and engineers. <i>Journal of Medical Engineering and Technology</i> , 2018 , 42, 435-442	1.8	4
5	Progress towards filling through silicon vias with conductive ink 2012 ,		3
4	Statistical analysis of stencil technology for wafer-level bumping. <i>Soldering and Surface Mount Technology</i> , 2014 , 26, 71-78	1.4	1
3	P-164: Electrical Characterisation and Modeling of Top-Emitting PIN-OLED Devices. <i>Digest of Technical Papers SID International Symposium</i> , 2010 , 41, 1863	0.5	1
2	Fabrication of Silicon Microchannel With Integrated Heater and Temperature Sensors for Flow Boiling Studies 2008 ,		1
1	Integrated Front End Circuitry for Microultrasound Capsule Endoscopy 2018 ,		1